

| | L # | Hits | Search Text | DBs | Time Stamp |
|----|-----|-------|--|---|------------------|
| 1 | L1 | 4774 | MEMS or microelectromechanical or micromechanical or (micro adj (mechanical or electromechanical or (electro adj mechanical))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 10:35 |
| 2 | L8 | 242 | 1 and ((resin resist photoresist epoxy polymer organic) near15 (sacrificial spacer removable disposable)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 11:47 |
| 3 | L15 | 641 | 1 and sealed | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 10:38 |
| 4 | L22 | 62 | 8 and sealed | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 11:27 |
| 5 | L29 | 2991 | microfabricat\$3 or (micro adj fabricat\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 11:28 |
| 6 | L36 | 7288 | 1 29 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 11:28 |
| 7 | L43 | 52 | 29 and 8 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 11:46 |
| 8 | L50 | 7285 | micromachin\$3 or (micro adj machin\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 11:47 |
| 9 | L57 | 1077 | 50 and sealed | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 11:48 |
| 10 | L64 | 249 | 50 and ((resin resist photoresist epoxy polymer organic) near15 (sacrificial spacer removable disposable)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 11:48 |
| 11 | L71 | 78 | 64 and sealed | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 11:52 |
| 12 | L78 | 12846 | 36 50 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 12:22 |
| 13 | L85 | 118 | 78 and (vapor near3 etch\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 12:23 |
| 14 | L92 | 19 | 85 and (vapor near3 etch\$3 near20 (HF or hydrofluoric)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 14:02 |
| 15 | L99 | 9 | ("5083857" "5099353" "5018256" "5142405").pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2001/05/31 14:03 |